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- **SPINOLA DURANTE, Guido**
6003 Luzern (CH)
- **BOSSHARD, Christian**
4415 Lansen (CH)

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(74) Representative: **Gevers SA**

Rue des Noyers 11
2000 Neuchâtel (CH)

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(73) Proprietor: **CSEM Centre Suisse d'Electronique et de**

Microtechnique SA - Recherche et Développement
2002 Neuchâtel (CH)

(56) References cited:

WO-A2-2012/015756 US-A- 5 738 270
US-A1- 2003 071 283

(72) Inventors:

- **JOSE JAMES, Rony**
6055 Alpanach Dorf (CH)

- **A. FAN ET AL: "Copper Wafer Bonding", ELECTROCHEMICAL AND SOLID-STATE LETTERS, vol. 2, no. 10, 1 January 1999 (1999-01-01), page 534, XP055088560, ISSN: 1099-0062, DOI: 10.1149/1.1390894**

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